

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Ling Chen et al.

Serial No.: 10/741,824

Confirmation No.: 2621

Filed: December 19, 2003

For: Enhancement of CU Line
Reliability Using Thin ALD Tan
Film to Cap the CU Line

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Group Art Unit: 2823

Examiner: John M. Parker

Do not Enter 12/14
JMP

MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

RESPONSE TO FINAL OFFICE ACTION DATED OCTOBER 03, 2006

In response to the Final Office Action dated October 3, 2006, having a shortened statutory period for response set to expire on January 3, 2007, please enter this response and reconsider the claims pending in the application for the reasons discussed below. Although Applicants believe that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/007532/KMT for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper. **Remarks** begin on page 7 of this paper.